

FIG.1

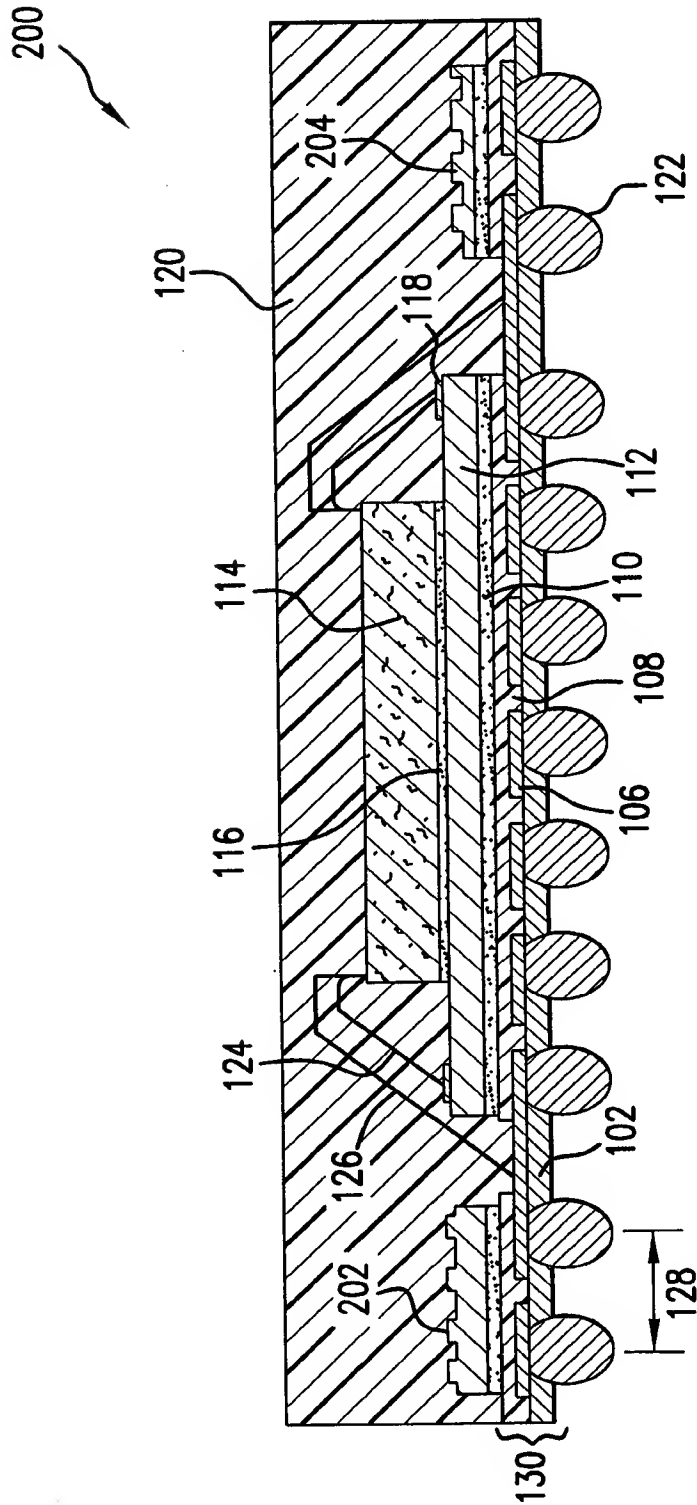


FIG.2



FIG. 4



FIG. 5

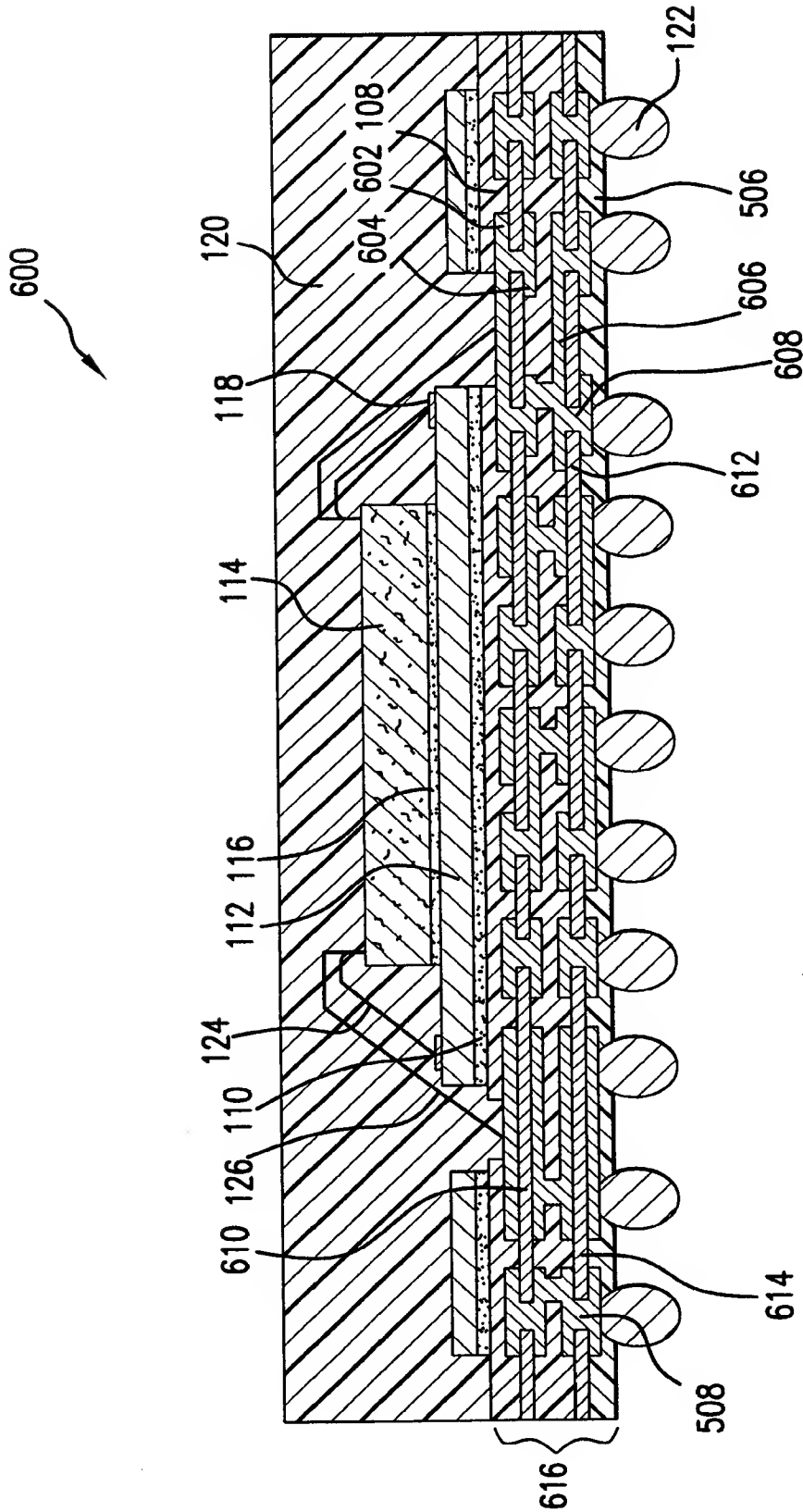


FIG. 6

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 Inventor(s): Zhao *et al.*; Tel: 202/371-2600
 Title: Thermally and Electrically Enhanced Ball Grid Array
 Packagaing

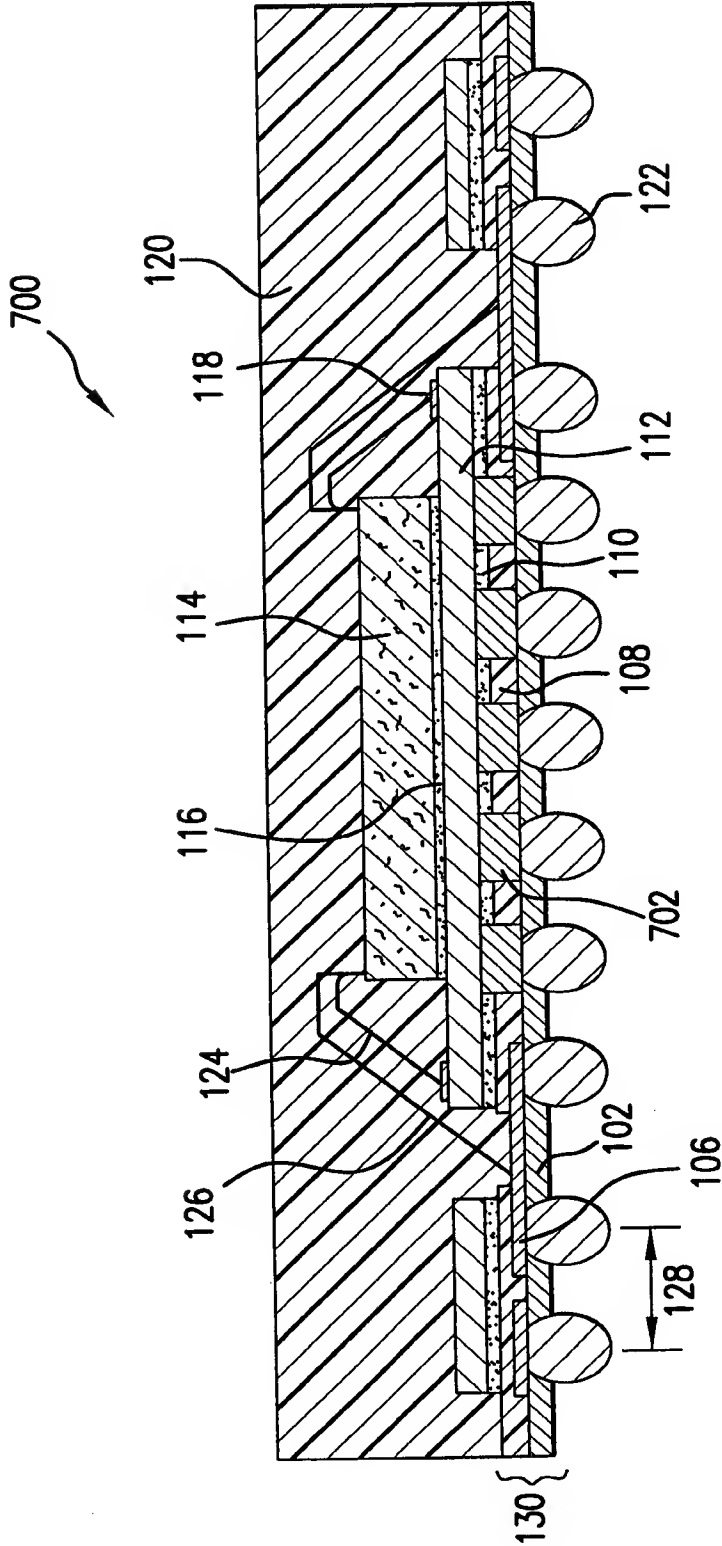


FIG.7

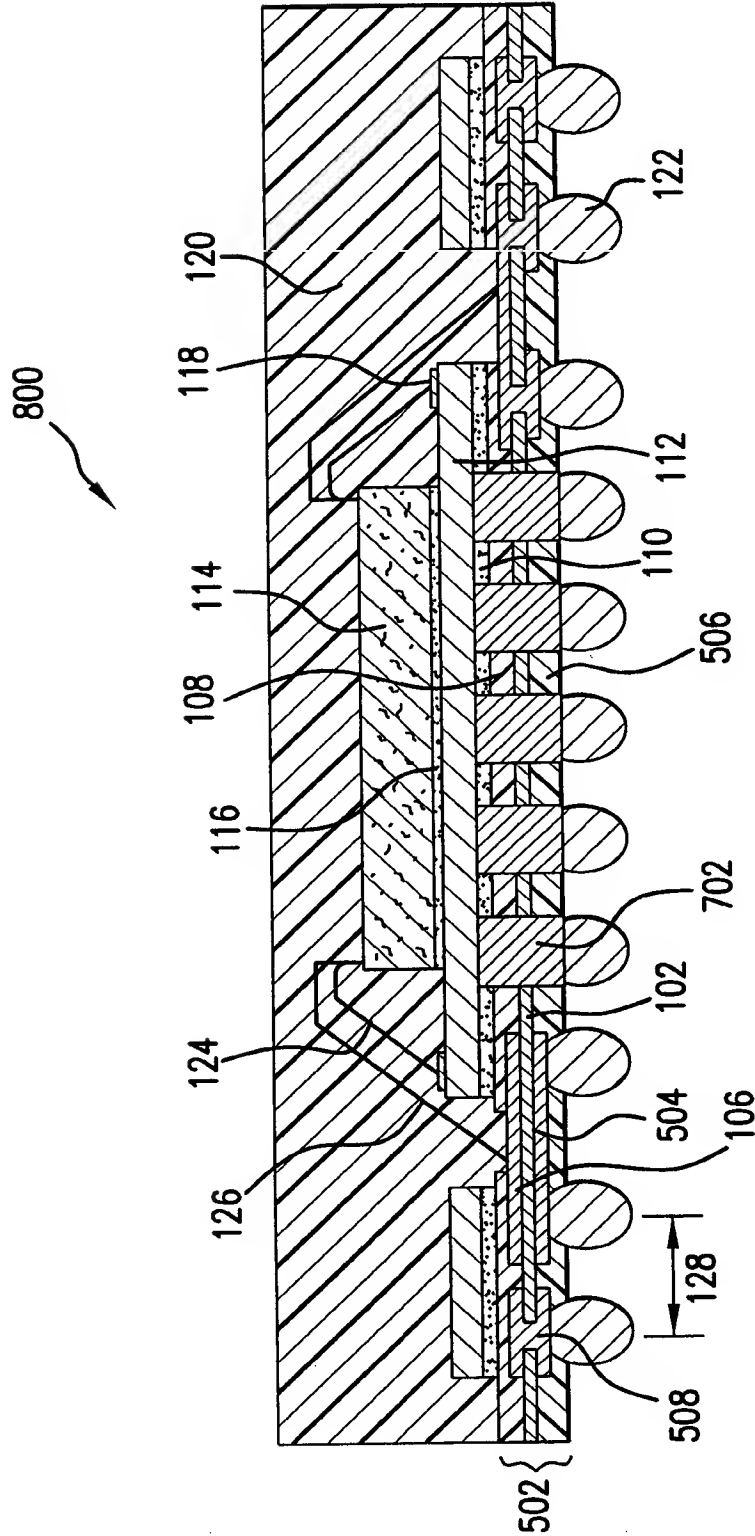


FIG.8





FIG. 10

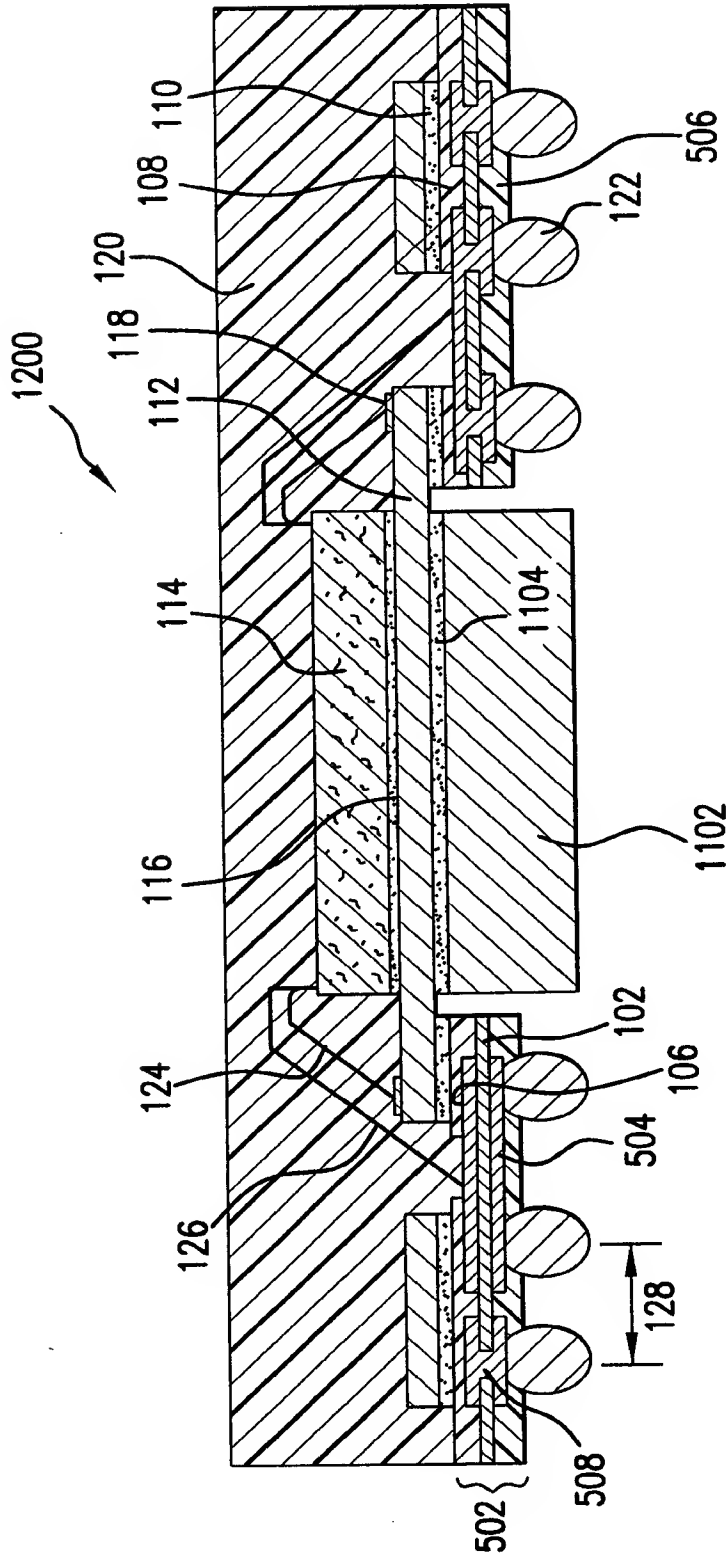


FIG.12

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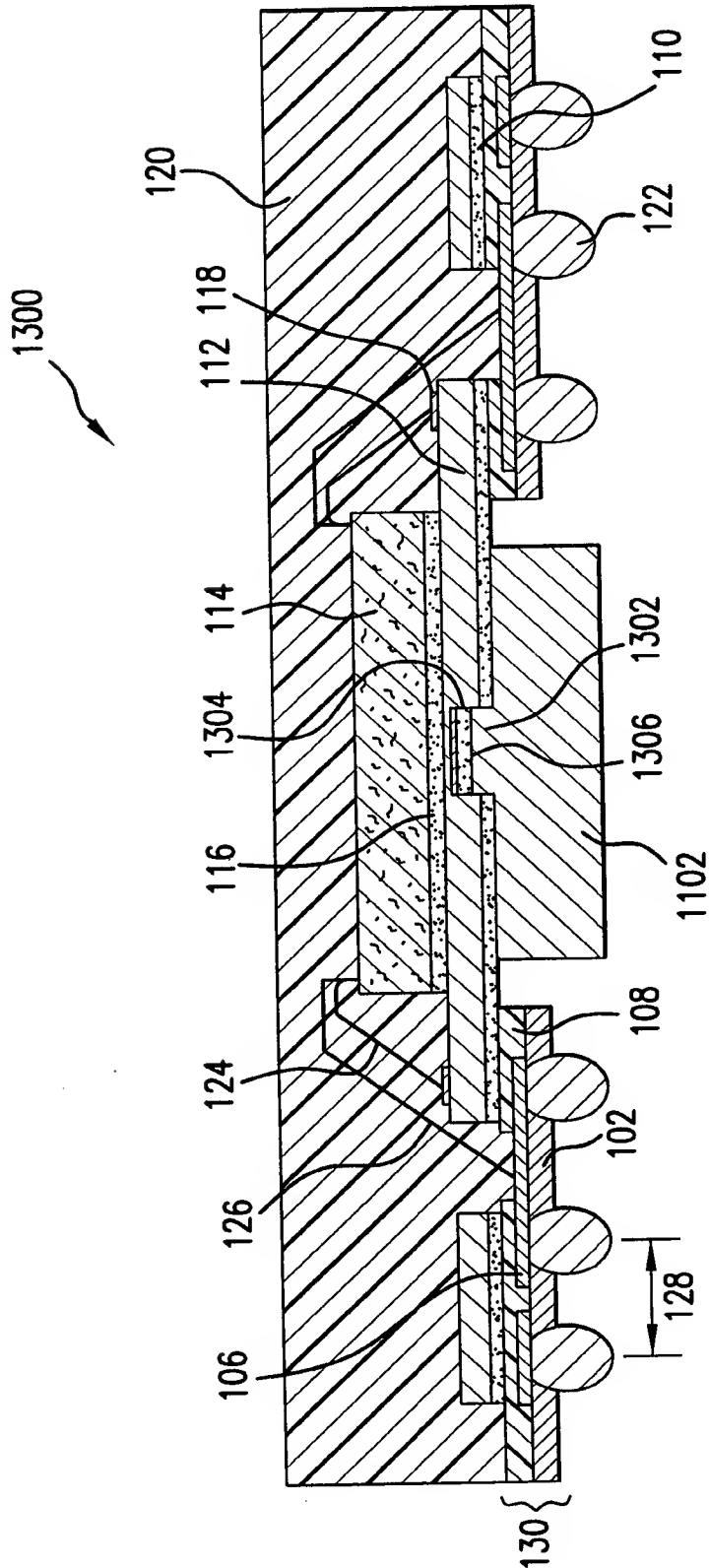
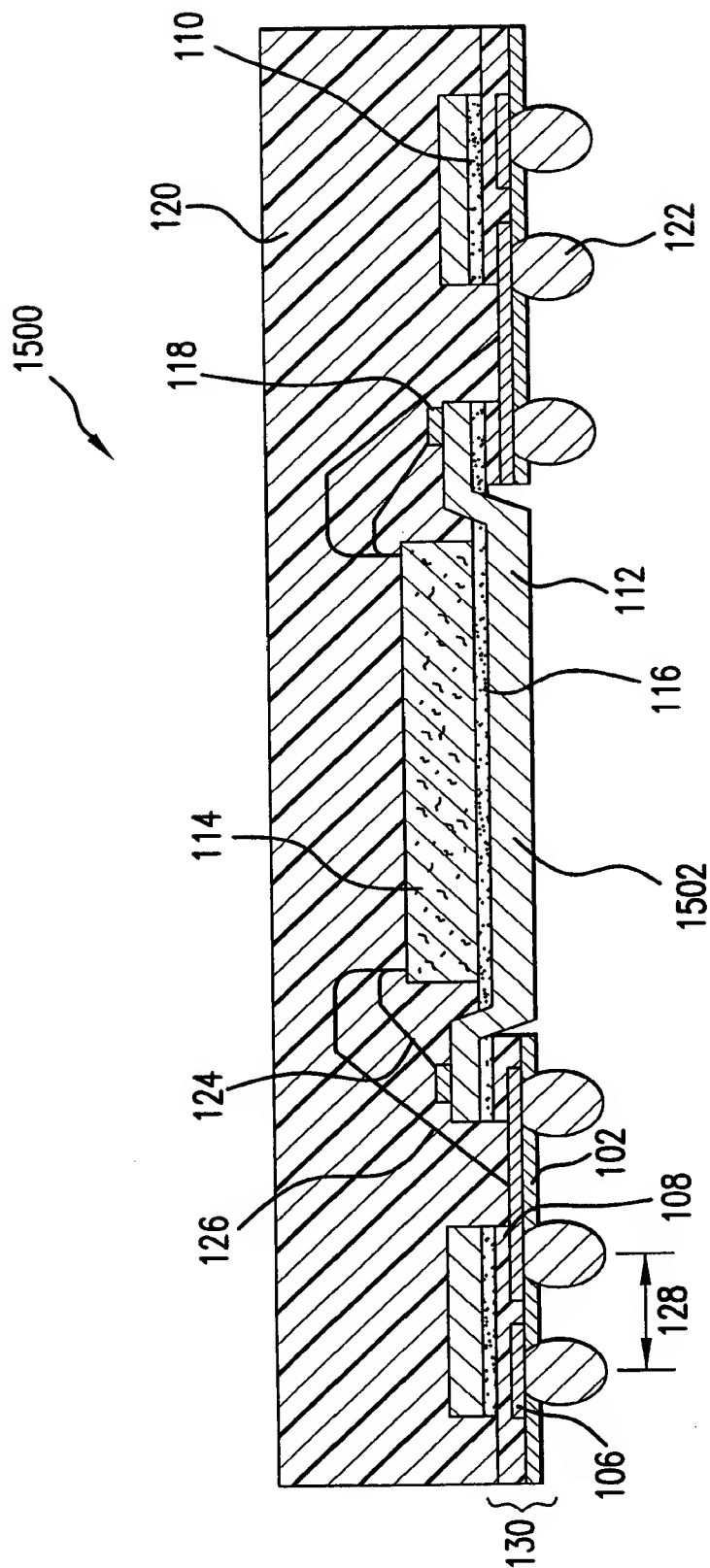


FIG. 13



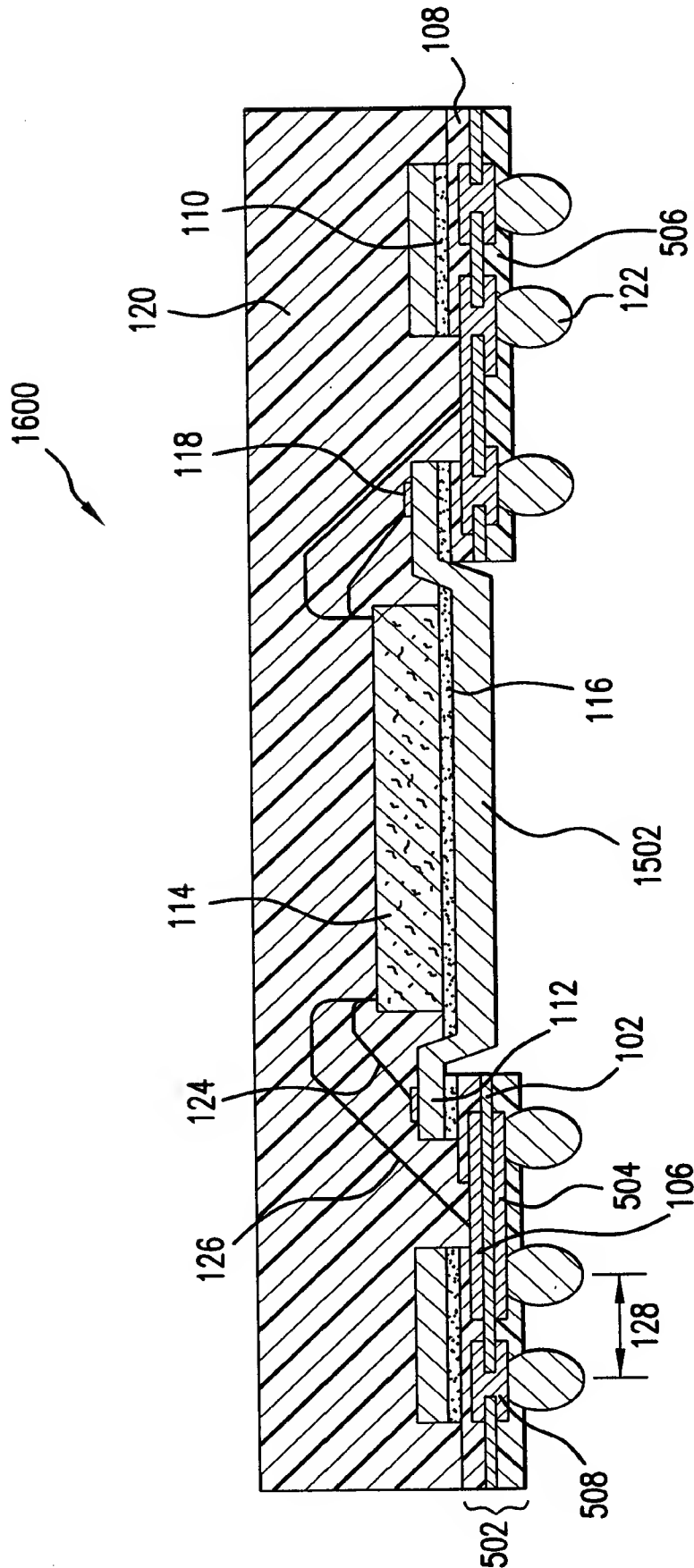


FIG.16

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Inventor(s): Zhao *et al.*; Tel: 202/371-2600
Title: Thermally and Electrically Enhanced Ball Grid Array
Packaging

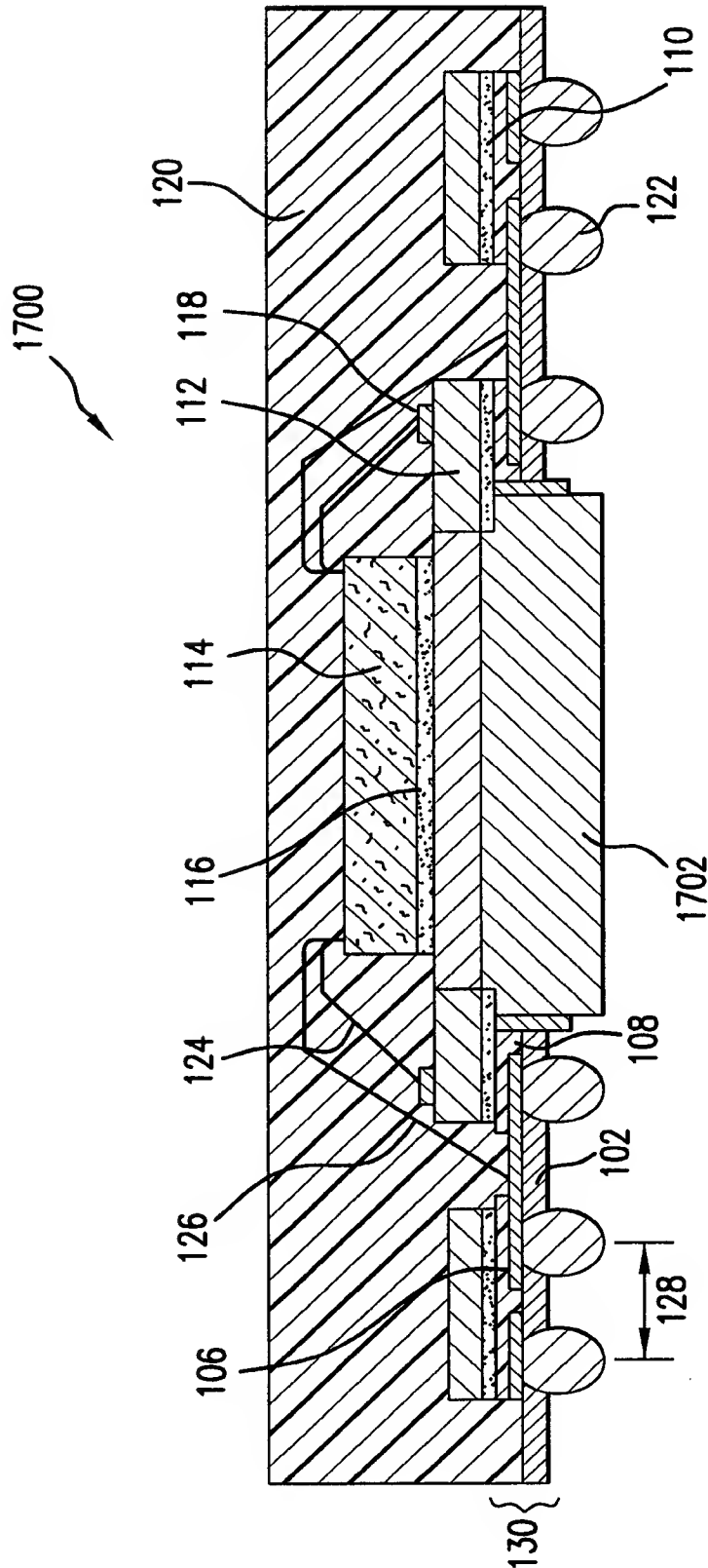


FIG. 17

